



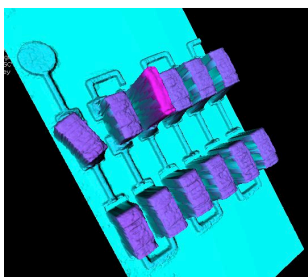
Since 1993 MVP have been innovating in the SMT industry. Our latest products combine measurement based SMT inspection with High Resolution 3D inspection to provide the most comprehensive inspection tool suite.

Our high accuracy height measurements are made using 3D profiler measurement systems and, the highest resolution optics available for SMT inspection.

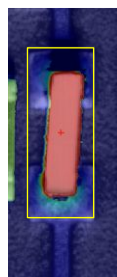
Combining “Measurement Based Inspection” and “3D inspection” techniques allow us to go far beyond comparative or template-based defect detection. Our capabilities include:

- **Measurements Capabilities Include:**  
Part position, % on pad, Rotation, % Solder, BGA collapse height, Part Dimensions, OCV, OCR, Pin vs Pad Positions, Die, Surface Inspection, FM Inspection, Partial Sizes, Underfill and Epoxy.
- **Defect Detection Capabilities Include:**  
Presence/Absence, Part Marking, Polarity, Head-in-Pillow, Tombstone, Billboard, Shorts/Opens, Bridge, Excess Solder, Insufficient Solder, Solder balls, Lifted leads, Component Damage, PTH defects.

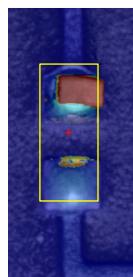
For program generation we provide several on-line and off-line automated tools that allow you to create recipes directly from CAD or Gerber. Repair and Data reporting is also available off-line, or web based.



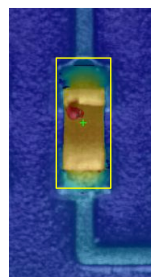
3D Overview



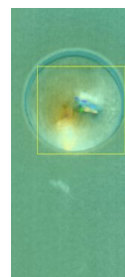
Billboard



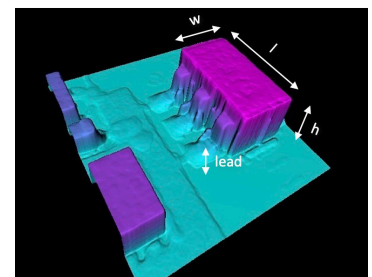
Tombstone



FM



Pin Hole



Measurement

In addition, our AutoData tools can provide full traceability. Options also allow for Image archiving and full variable data retention. For more information, please contact MVP.